

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) An encapsulated organic optoelectronic device, comprising:
 - a substrate;
 - an organic optoelectronic device on said substrate, said organic optoelectronic device includes a cathode;
 - a diffusion layer on said organic optoelectronic device, said diffusion layer covers exposed areas of said organic optoelectronic device;
 - an adhesive layer on said substrate and around a perimeter of said diffusion layer, wherein said adhesive layer is separated from said diffusion layer by a gap such that said adhesive layer does not physically contact said diffusion layer;
 - an encapsulation lid on said adhesive layer, said encapsulation lid forming a cavity around said organic optoelectronic device such that there is a gap between said encapsulation lid and said diffusion layer; and
 - a getter on said encapsulation lid, said getter overlies said organic optoelectronic device,
 - wherein said diffusion layer slows a rate of absorption of reactive gasses by said cathode and increases a proportion of said reactive gasses absorbed by said getter relative to said cathode.
2. (Original) The encapsulated organic optoelectronic device of claim 1 wherein said diffusion layer is a solvent-free organic polymer layer.
3. (Original) The encapsulated organic optoelectronic device of claim 1 wherein said diffusion layer is a solvent-free UV-curable acrylate material.

4. (Original) The encapsulated organic optoelectronic device of claim 1 wherein said diffusion layer is a UV-curable or thermally-curable solvent-free epoxy.
5. (Original) The encapsulated organic optoelectronic device of claim 1 wherein said diffusion layer is a solvent-free photoresist.
6. (Original) The encapsulated organic optoelectronic device of claim 1 wherein said reactive gasses are oxygen and moisture.
7. (Original) The encapsulated organic optoelectronic device of claim 1 wherein said getter has a relatively slow rate of absorption compared to a rate of absorption of said cathode.
8. (Original) The encapsulated organic optoelectronic device of claim 1 wherein said organic optoelectronic device is any one of:
an OLED display, an organic light sensor array, an organic solar cell array, or an organic laser.
9. (Withdrawn) A method to encapsulate an organic optoelectronic device, comprising:
fabricating said organic optoelectronic device on a substrate, said organic optoelectronic device includes a cathode;
depositing a diffusion layer on said organic optoelectronic device, said diffusion layer covers exposed areas of said organic optoelectronic device;
depositing an adhesive layer on an encapsulation lid or on said substrate around a perimeter of said diffusion layer such that when said adhesive layer, said encapsulation lid, and said substrate are brought together, said organic optoelectronic device is sealed; and
attaching a getter to said encapsulation lid such that when said adhesive layer, said encapsulation lid, and said substrate are brought together, said getter overlies said organic optoelectronic device.

10. (Withdrawn) The method of claim 9 further comprising bringing together said encapsulation lid and said substrate such that said adhesive layer bonds with both said substrate and said encapsulation lid to seal said organic optoelectronic device.
11. (Withdrawn) The method of claim 9 wherein said diffusion layer slows a rate of absorption of reactive gasses by said cathode and increases a proportion of said reactive gasses absorbed by said getter in relation to said cathode.
12. (Withdrawn) The method of claim 9 wherein said diffusion layer is a solvent-free organic polymer layer.
13. (Withdrawn) The method of claim 9 wherein said diffusion layer is a solvent-free UV-curable acrylate material.
14. (Withdrawn) The method of claim 9 wherein said diffusion layer is a UV-curable or thermally-curable solvent-free epoxy.
15. (Withdrawn) The method of claim 9 wherein said diffusion layer is a solvent-free photoresist.
16. (Withdrawn) The method of claim 9 wherein said organic optoelectronic device is any one of: an OLED display, an organic light sensor array, an organic solar cell array, or an organic laser.
17. (Withdrawn) A method to encapsulate an organic optoelectronic device, comprising:
 - fabricating said organic optoelectronic device on a substrate, said organic optoelectronic device includes a cathode;
 - attaching a getter to an encapsulation lid; and
 - slowing a rate of absorption of reactive gasses by said cathode, and

increasing a proportion of said reactive gasses absorbed by said getter relative to said cathode by depositing a diffusion layer on said organic optoelectronic device, said diffusion layer covers exposed areas of said organic optoelectronic device.

18. (Withdrawn) The method of claim 17 further comprising bonding together said encapsulation lid and said substrate to seal said organic optoelectronic device.

19. (Withdrawn) The method of claim 17 wherein said diffusion layer is a solvent-free organic polymer layer.

20. (Withdrawn) The method of claim 17 wherein said diffusion layer is a solvent-free UV-curable acrylate material.

21. (Withdrawn) The method of claim 17 wherein said diffusion layer is a UV-curable or thermally-curable solvent-free epoxy.

22. (Withdrawn) The method of claim 17 wherein said diffusion layer is a solvent-free photoresist.

23. (Withdrawn) The method of claim 17 wherein said organic optoelectronic device is any one of: an OLED display, an organic light sensor array, an organic solar cell array, or an organic laser.

24. (New) The encapsulated organic optoelectronic device of claim 1, wherein said diffusion layer does not physically contact said getter.

25. (New) An encapsulated organic optoelectronic device, comprising:
a substrate;
an organic optoelectronic device on said substrate, said organic optoelectronic device including a cathode;
a diffusion layer on said organic optoelectronic device, said diffusion layer covering exposed areas of said organic optoelectronic device;

an adhesive layer on said substrate and around a perimeter of said diffusion layer;
an encapsulation lid on said adhesive layer; and
a getter on said encapsulation lid, wherein said getter overlies said organic optoelectronic device, said getter is spaced from said diffusion layer by a gap, and said encapsulation lid with said getter forms a cavity around said organic optoelectronic device.